ChunZheng

High-end Power Semiconductor Manufacturer

KP500A 1000V-1800V
Phase Control Thyristor

- High power cycling capability
- Low on-state and switching losses
- Designed for traction and industrial applications

Mean on-state current			I_{TAV}	500 A	
Repetitive peak off-state voltage			V_{DRM}	1000 – 1800 V	
Repetitive peak reverse voltage			V_{RRM}		
Turn-off time			t_q	160 µs	
V_{DRM}, V_{RRM}, V	1000	1200	1400	1600	1800
Voltage code	10	12	14	16	18
T_j, °C	-60 – 125				

MAXIMUM ALLOWABLE RATINGS

Symbols and parameters		Units	Values	Test conditions	
ON-STATE					
I_{TAV}	Mean on-state current	A	500	T_c=85 °C, Double side cooled 180° half-sine wave; 50 Hz	
I_{TRMS}	RMS on-state current	A	785	T_c=85 °C, Double side cooled 180° half-sine wave; 50 Hz	
I_{TSM}	Surge on-state current	kA	11.0 13.0	T_j=$T_{j\,max}$ T_j=25 °C	180° half-sine wave; 50 Hz (t_p=10 ms); single pulse; V_D=V_R=0 V; Gate pulse:I_G=I_{FGM}; V_G=20 V; t_{GP}=500 µs; di_G/dt=1 A/µs
			12.0 24.0	T_j=$T_{j\,max}$ T_j=25 °C	180° half-sine wave; 60 Hz (t_p=8.3 ms); single pulse; V_D=V_R=0 V; Gate pulse:I_G=I_{FGM}; V_G=20 V; t_{GP}=500 µs; di_G/dt=1 A/µs
I^2t	Safety factor	$A^2s\cdot10^3$	605 845	T_j=$T_{j\,max}$ T_j=25 °C	180° half-sine wave; 50 Hz (t_p=10 ms); single pulse; V_D=V_R=0 V; Gate pulse:I_G=I_{FGM}; V_G=20 V; t_{GP}=500 µs; di_G/dt=1 A/µs
			595 810	T_j=$T_{j\,max}$ T_j=25 °C	180° half-sine wave; 60 Hz (t_p=8.3 ms); single pulse; V_D=V_R=0 V; Gate pulse:I_G=I_{FGM}; V_G=20 V; t_{GP}=500 µs; di_G/dt=1 A/µs
BLOCKING					
V_{DRM}, V_{RRM}	Repetitive peak off-state and Repetitive peak reverse voltages	V	1000 – 1800	$T_{j\,min}$< T_j <$T_{j\,max}$; 180° half-sine wave; 50 Hz; Gate open	
V_{DSM}, V_{RSM}	Non-repetitive peak off-state and Non-repetitive peak reverse voltages	V	1100 – 1900	$T_{j\,min}$< T_j <$T_{j\,max}$; 180° half-sine wave; 50 Hz;single pulse; Gate open	
V_D, V_R	Direct off-state and Direct reverse voltages	V	0.75·V_{DRM} 0.75·V_{RRM}	T_j=$T_{j\,max}$; Gate open	

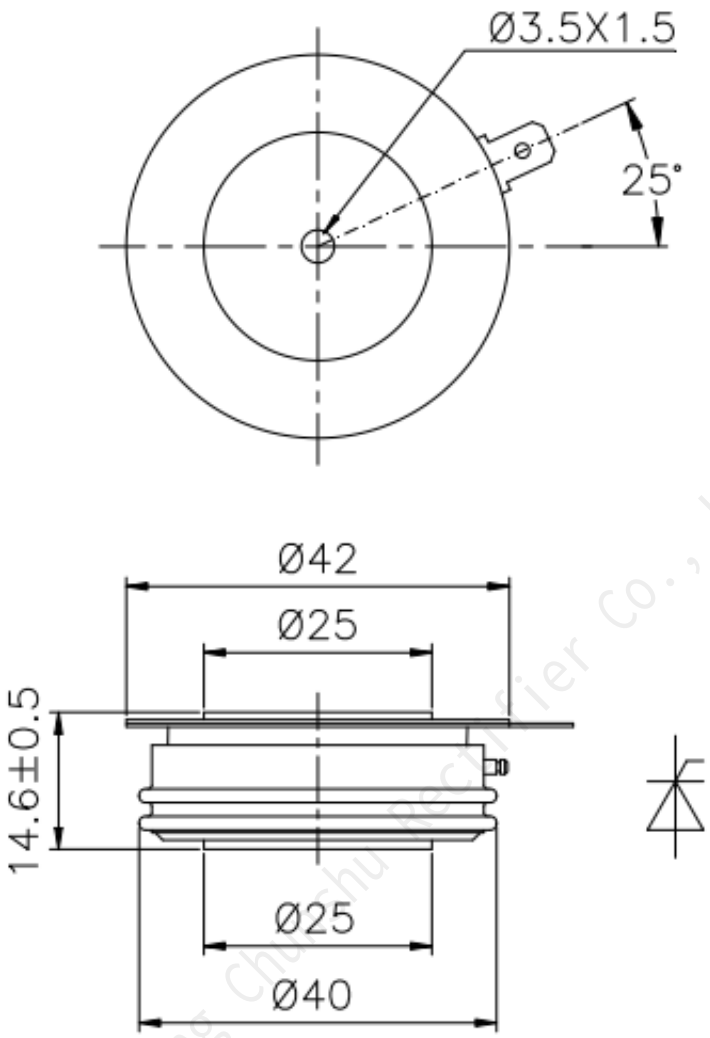
TRIGGERING				
I_{FGM}	Peak forward gate current	A	8	$T_j=T_{j\,max}$
V_{RGM}	Peak reverse gate voltage	V	5	
P_G	Gate power dissipation	W	4	$T_j=T_{j\,max}$ for DC gate current
SWITCHING				
$(di_T/dt)_{crit}$	Critical rate of rise of on-state current non-repetitive (f=1 Hz)	A/μs	200	$T_j=T_{j\,max}$; $V_D=0.67\cdot V_{DRM}$; $I_{TM}=2\ I_{TAV}$; Gate pulse: $I_G=I_{FGM}$; $V_G=20$ V; $t_{GP}=500$ μs; $di_G/dt=1$ A/μs
THERMAL				
T_{stg}	Storage temperature	°C	-60…125	
T_j	Operating junction temperature	°C	-60…125	
MECHANICAL				
F	Mounting force	kN	14.0…16.0	
a	Acceleration	m/s^2	50 100	Device unclamped Device clamped

CHARACTERISTICS

Symbols and parameters		Units	Values	Conditions	
ON-STATE					
V_{TM}	Peak on-state voltage, max	V	2.00	$T_j=25$ °C; $I_{TM}=1570$ A	
$V_{T(TO)}$	On-state threshold voltage, max	V	1.15	$T_j=T_{j\,max}$; $0.5\ \pi\ I_{TAV} < I_T < 1.5\ \pi\ I_{TAV}$	
r_T	On-state slope resistance, max	mΩ	0.590		
I_L	Latching current, max	mA	1000	$T_j=25$ °C; $V_D=12$ V; Gate pulse: $I_G=I_{FGM}$; $V_G=20$ V; $t_{GP}=500$ μs; $di_G/dt=1$ A/μs	
I_H	Holding current, max	mA	300	$T_j=25$ °C; $V_D=12$ V; Gate open	
BLOCKING					
I_{DRM}, I_{RRM}	Repetitive peak off-state and Repetitive peak reverse currents, max	mA	100	$T_j=T_{j\,max}$; $V_D=V_{DRM}$; $V_R=V_{RRM}$	
$(dv_D/dt)_{crit}$	Critical rate of rise of off-state voltage[1], min	V/μs	1000	$T_j=T_{j\,max}$; $V_D=0.67\cdot V_{DRM}$; Gate open	
TRIGGERING					
V_{GT}	Gate trigger direct voltage, max	V	2.50 2.00	$T_j=25$ °C $T_j=T_{j\,max}$	$V_D=12$ V; $I_D=3$ A; Direct gate current
I_{GT}	Gate trigger direct current, max	mA	250 200	$T_j=25$ °C $T_j=T_{j\,max}$	
V_{GD}	Gate non-trigger direct voltage, min	V	0.25	$T_j=T_{j\,max}$; $V_D=0.67\cdot V_{DRM}$; Direct gate current	
I_{GD}	Gate non-trigger direct current, min	mA	10.00		
SWITCHING					
t_{gd}	Delay time	μs	2.00	$T_j=25$ °C; $V_D=0.4\cdot V_{DRM}$; $I_{TM}=I_{TAV}$; Gate pulse: $I_G=I_{FGM}$; $V_G=20$ V; $t_{GP}=500$ μs; $di_G/dt=1$ A/μs	
t_q	Turn-off time[2], max	μs	160	$dv_D/dt=50$ V/μs; $T_j=T_{j\,max}$; $I_{TM}=I_{TAV}$; $di_R/dt=-10$ A/μs; $V_R=100$V; $V_D=0.67\cdot V_{DRM}$	
Q_{rr}	Total recovered charge, max	μC	1500	$T_j=T_{j\,max}$; $I_{TM}=500$ A; $di_R/dt=-10$ A/μs; $V_R=100$ V;	
t_{rr}	Reverse recovery time, typ	μs	25		
I_{rrM}	Peak reverse recovery current, max	A	120		

THERMAL					
R_{thjc}	Thermal resistance, junction to case, max	°C/W	0.0320	Direct current	Double side cooled
R_{thjc-A}			0.0704		Anode side cooled
R_{thjc-K}			0.0576		Cathode side cooled
R_{thck}	Thermal resistance, case to heatsink, max	°C/W	0.0060	Direct current	
MECHANICAL					
w	Weight, typ	g	260		
D_s	Surface creepage distance	mm (inch)	19.44 (0.765)		
D_a	Air strike distance	mm (inch)	12.10 (0.476)		

OVERALL DIMENSIONS



KT30

All dimensions in millimeters

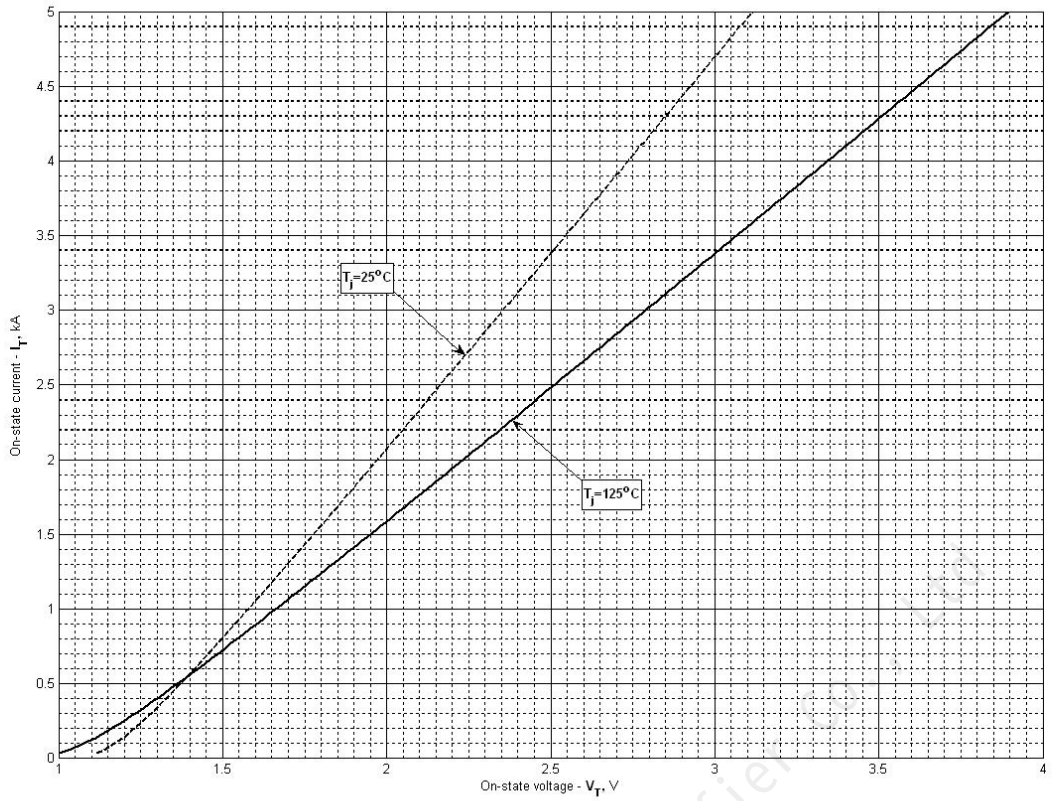


Fig 1 – On-state characteristics of Limit device

Analytical function for On-state characteristic:

$$V_T = A + B \times i_T + C \times \ln(i_T + 1) + D \times \sqrt{i_T}$$

	Coefficients for max curves	
	T_j = 25°C	$T_j = T_{j\,max}$
A	1.061292	0.926860
B	0.339787	0.498978
C	-0.181345	-0.242199
D	0.304070	0.406107

On-state characteristic model (see Fig. 1)

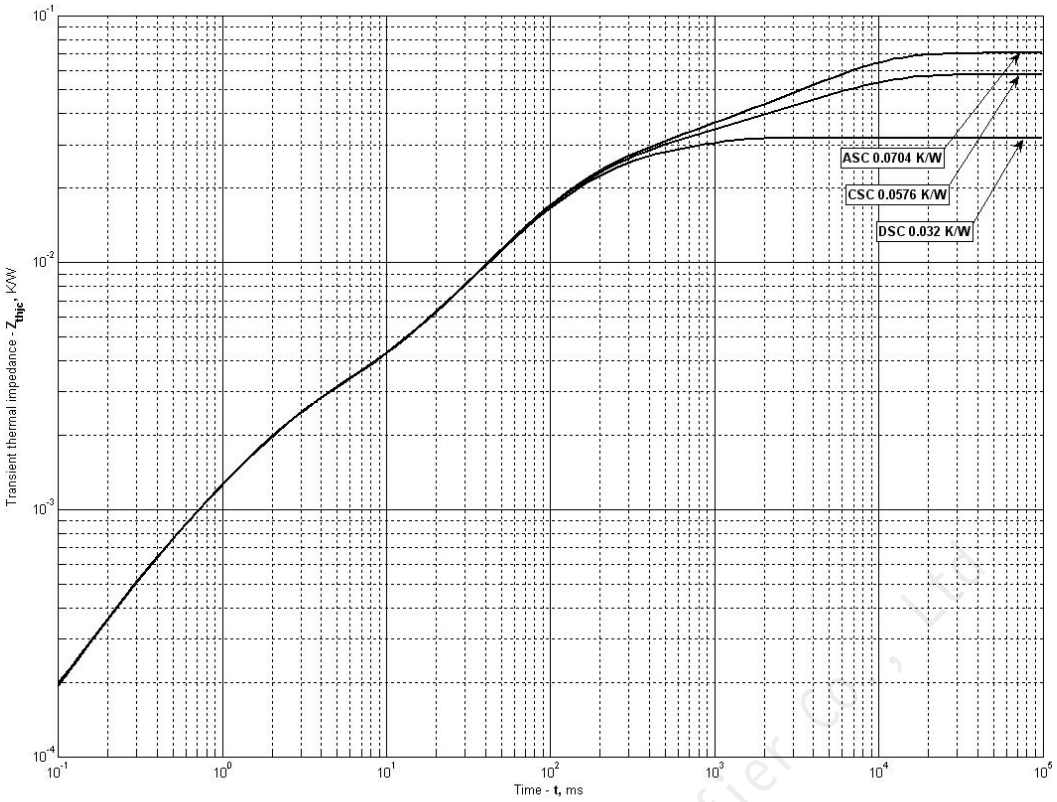


Fig 2 – Transient thermal impedance

Analytical function for Transient thermal impedance junction to case Z_{thjc} for DC:

$$Z_{thjc} = \sum_{i=1}^{n} R_i \left(1 - e^{-\frac{t}{\tau_i}}\right)$$

Where ***i*** = 1 to ***n***, ***n*** is the number of terms in the series.

t = Duration of heating pulse in seconds.

Z_{thjc} = Thermal resistance at time t.

R_i = Amplitude of p_{th} term.

τ_i = Time constatnt of r_{th} term.

DC Double side cooled

i	1	2	3	4	5	6
R_i, K/W	0.000005619	0.01031	0.01922	0.0004148	0.001895	0.0001521
τ_i, s	7.790	0.5094	0.09719	0.01725	0.0016	0.0002257

DC Anode side cooled

i	1	2	3	4	5	6
R_i, K/W	0.0381	0.008681	0.01867	0.001961	0.0001787	0.002771
τ_i, s	5.351	0.4584	0.09325	0.001734	0.0002174	0.9059

DC Cathode side cooled

i	1	2	3	4	5	6
R_i, K/W	0.02561	0.001472	0.01786	0.001926	0.0001928	0.01052
τ_i, s	5.328	0.1832	0.09031	0.001714	0.0002598	0.525

Transient thermal impedance junction to case Z_{thjc} model (see Fig. 2)

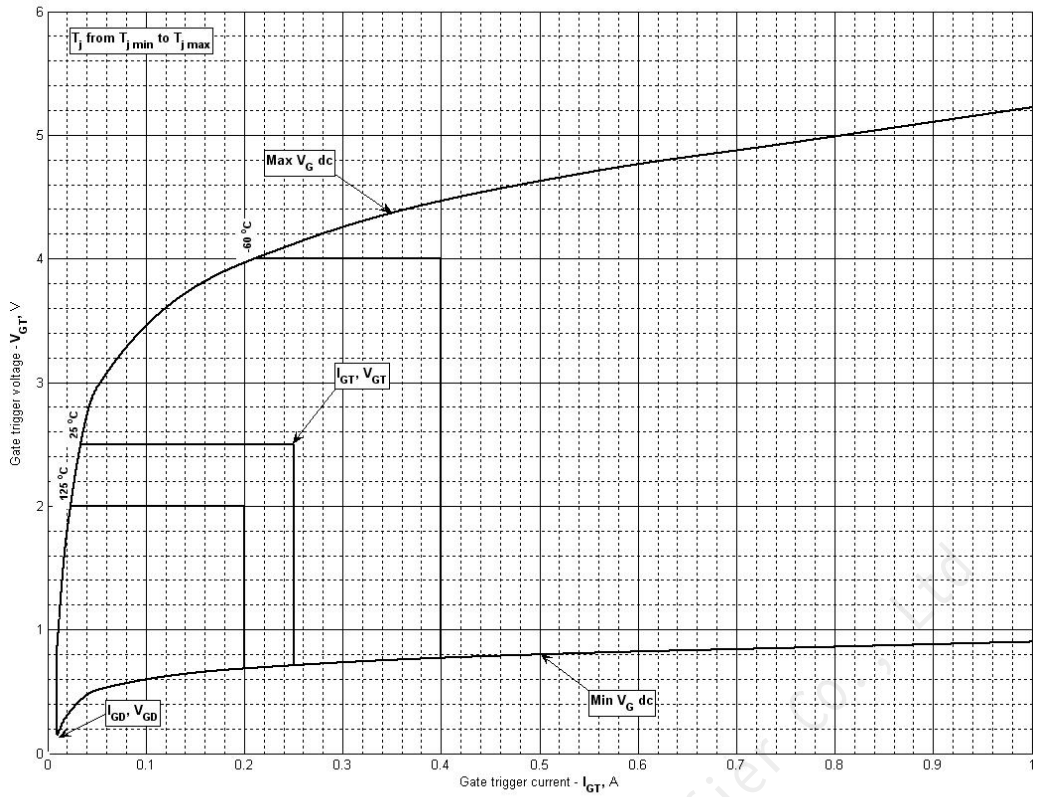


Fig 3 – Gate characteristics – Trigger limits

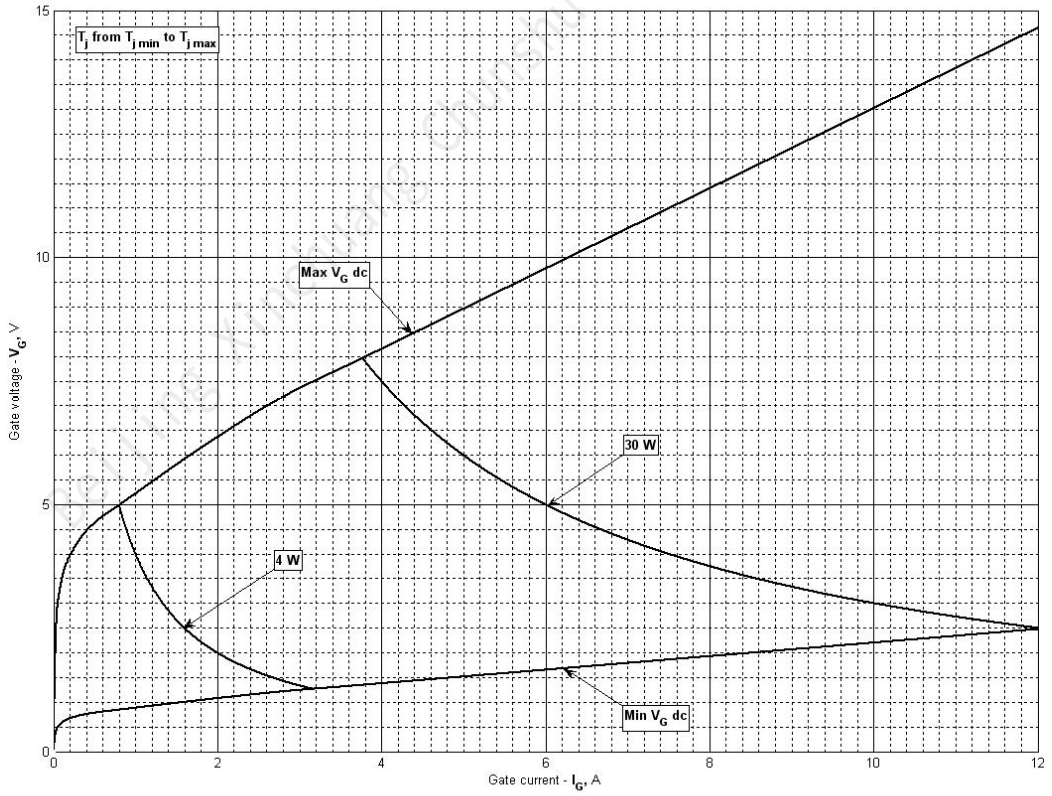


Fig 4 - Gate characteristics –Power curves

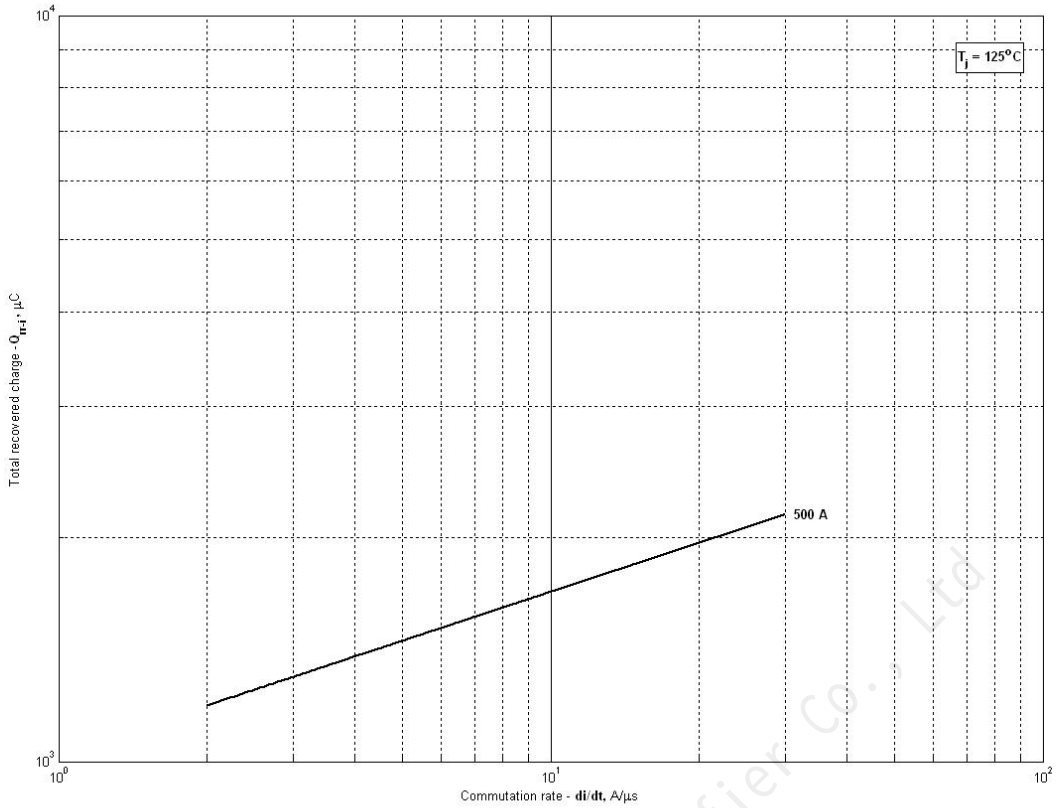


Fig 5 – Total recovered charge, Q_{rr-i} (integral)

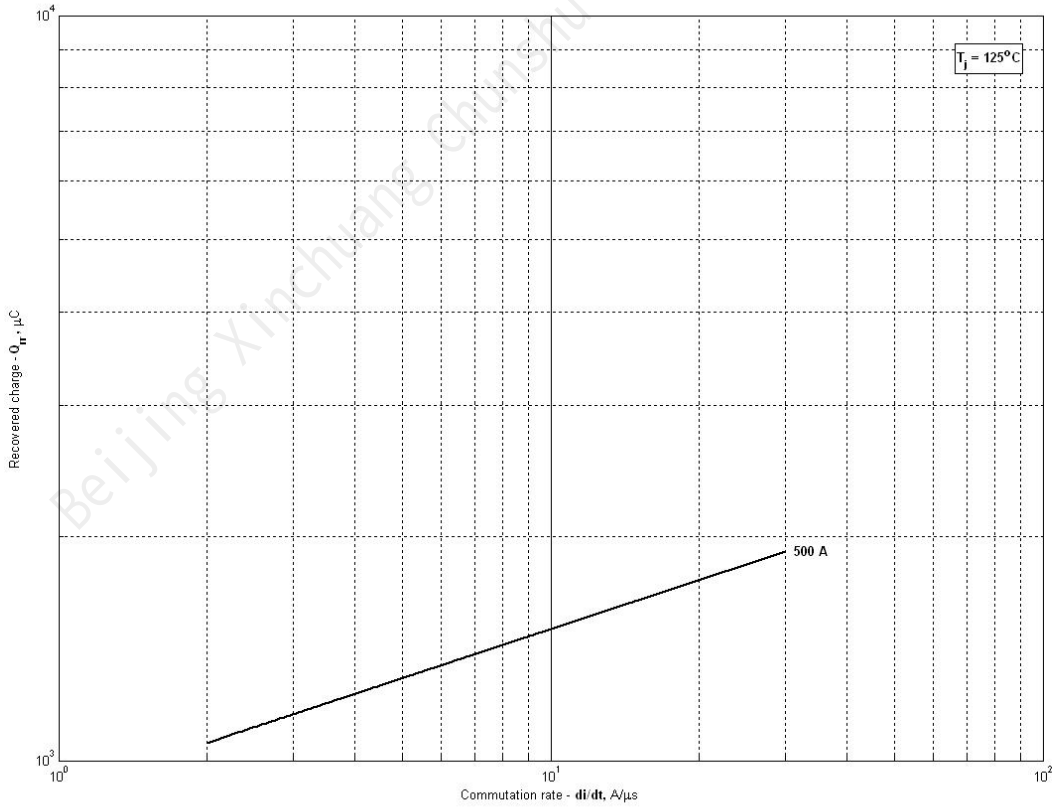


Fig 6 - Recovered charge, Q_{rr} (linear)

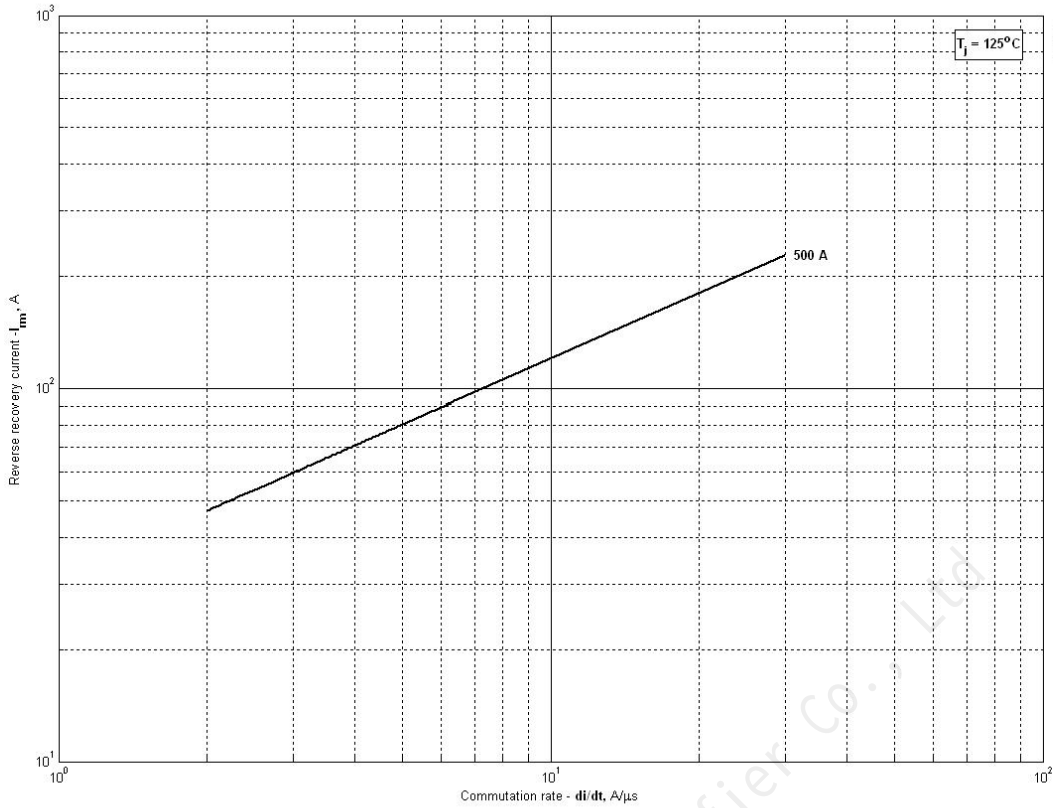


Fig 7 – Peak reverse recovery current, I_{rm}

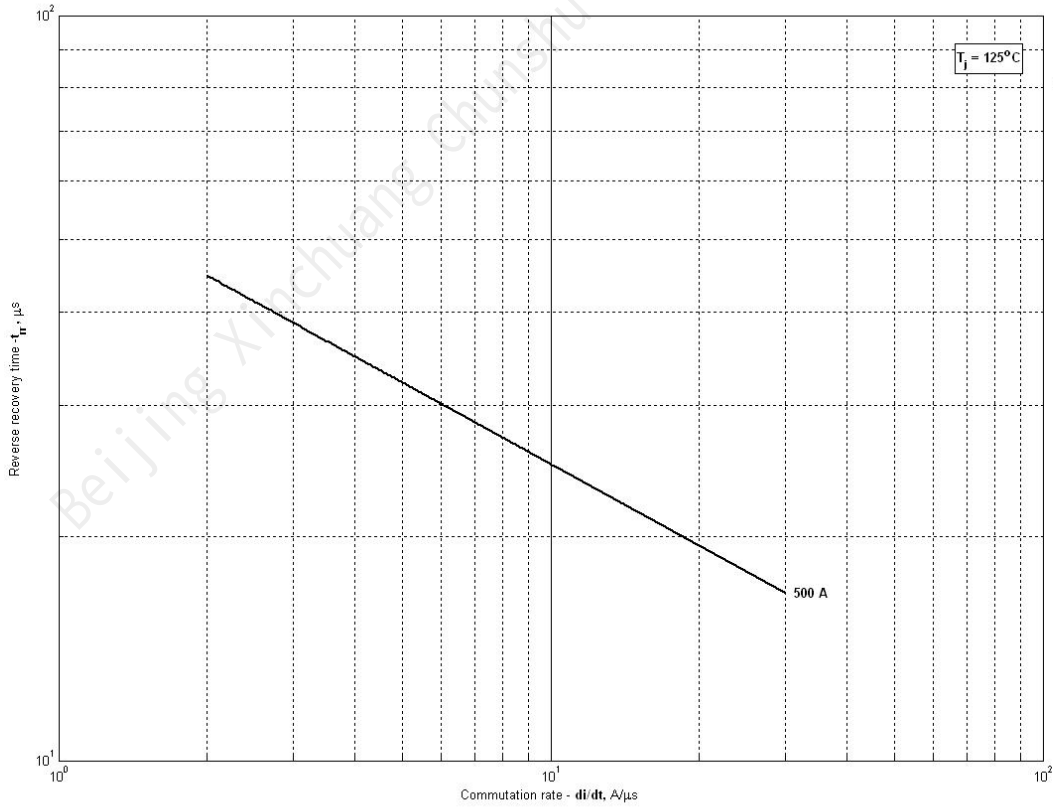


Fig 8 – Maximum recovery time, t_{rr} (linear)

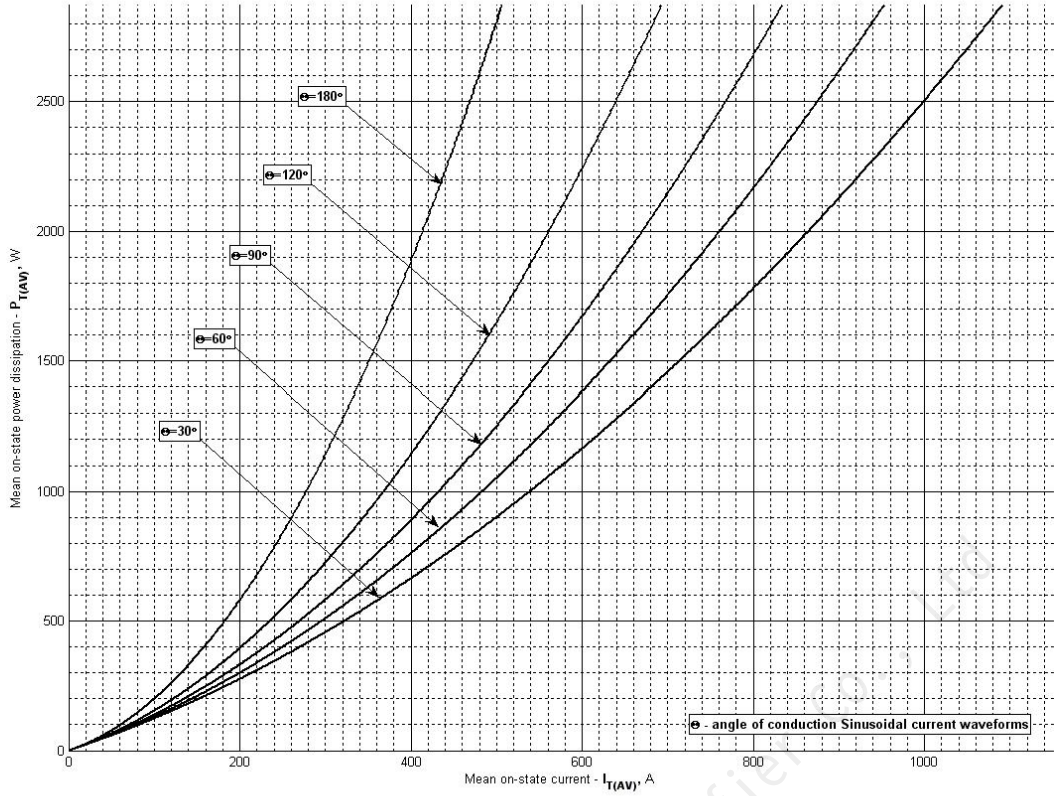


Fig 9 – On-state power loss (sinusoidal current waveforms)

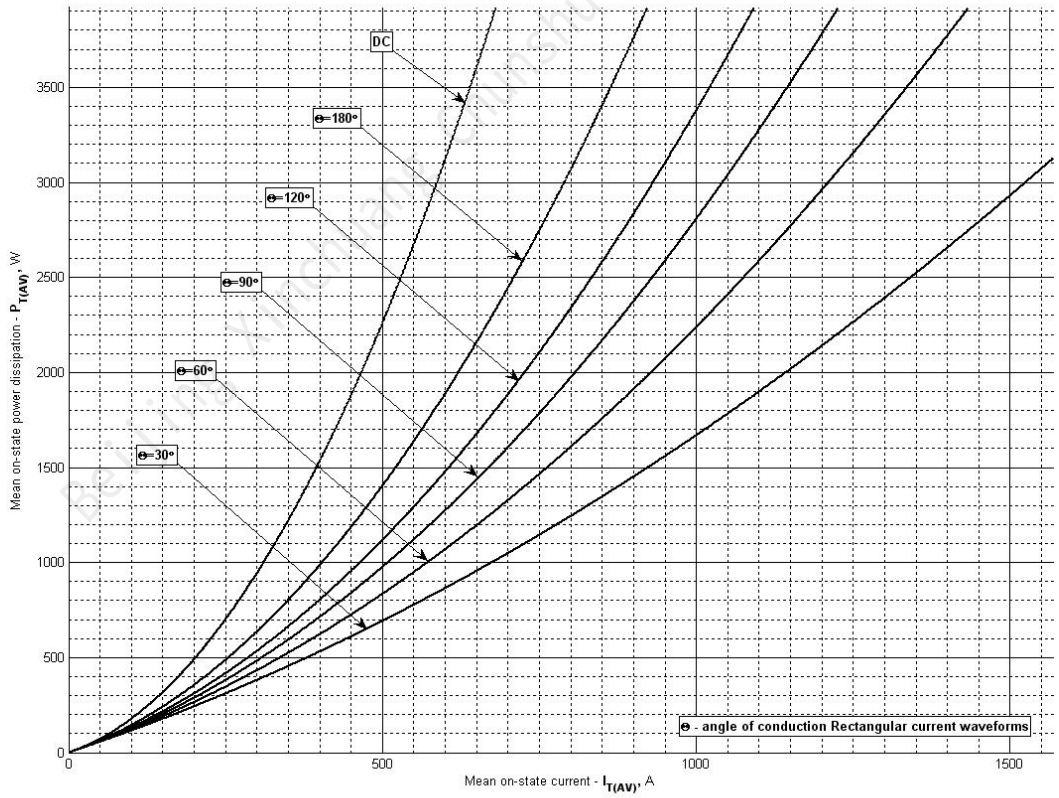


Fig 10 – On-state power loss (rectangular current waveforms)

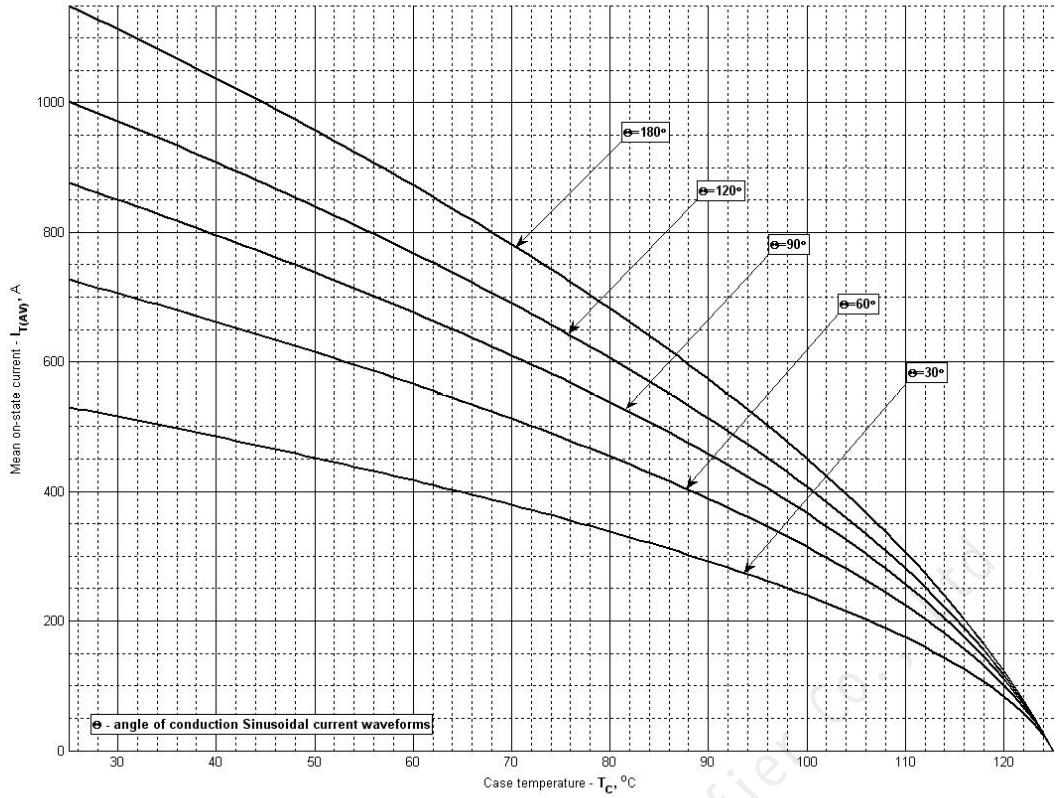


Fig 11 – Maximum case temperature DSC (sinusoidal current waveforms)

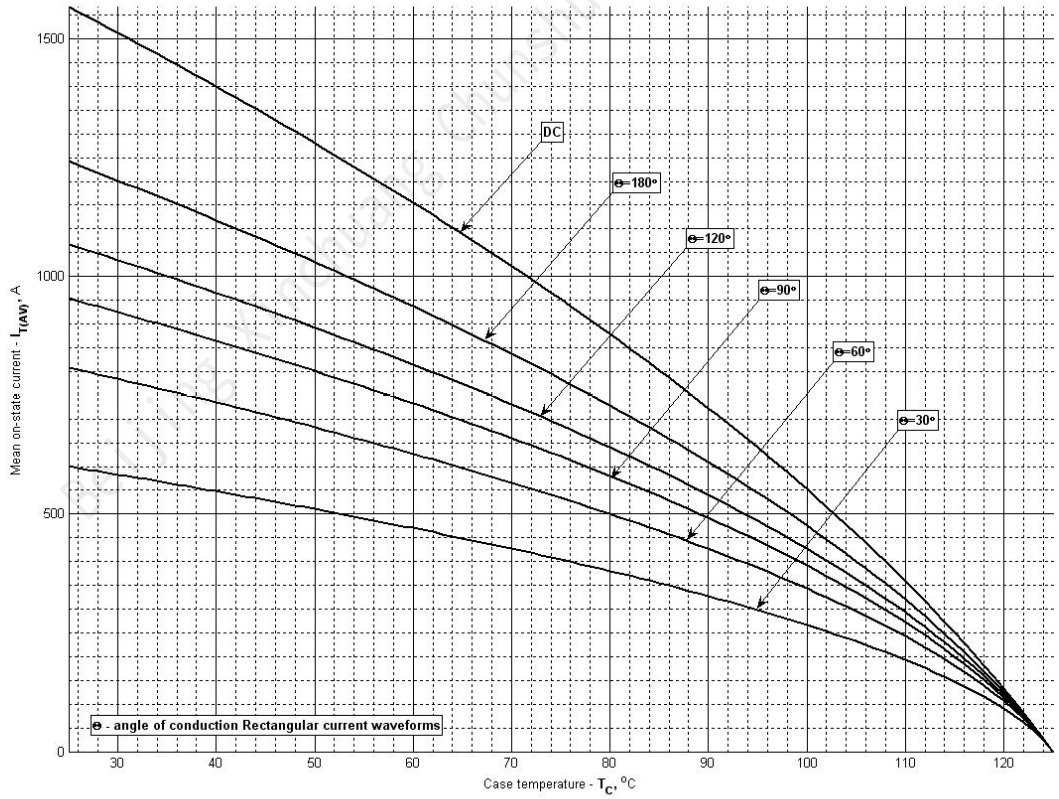


Fig 12 – Maximum case temperature DSC (rectangular current waveforms)

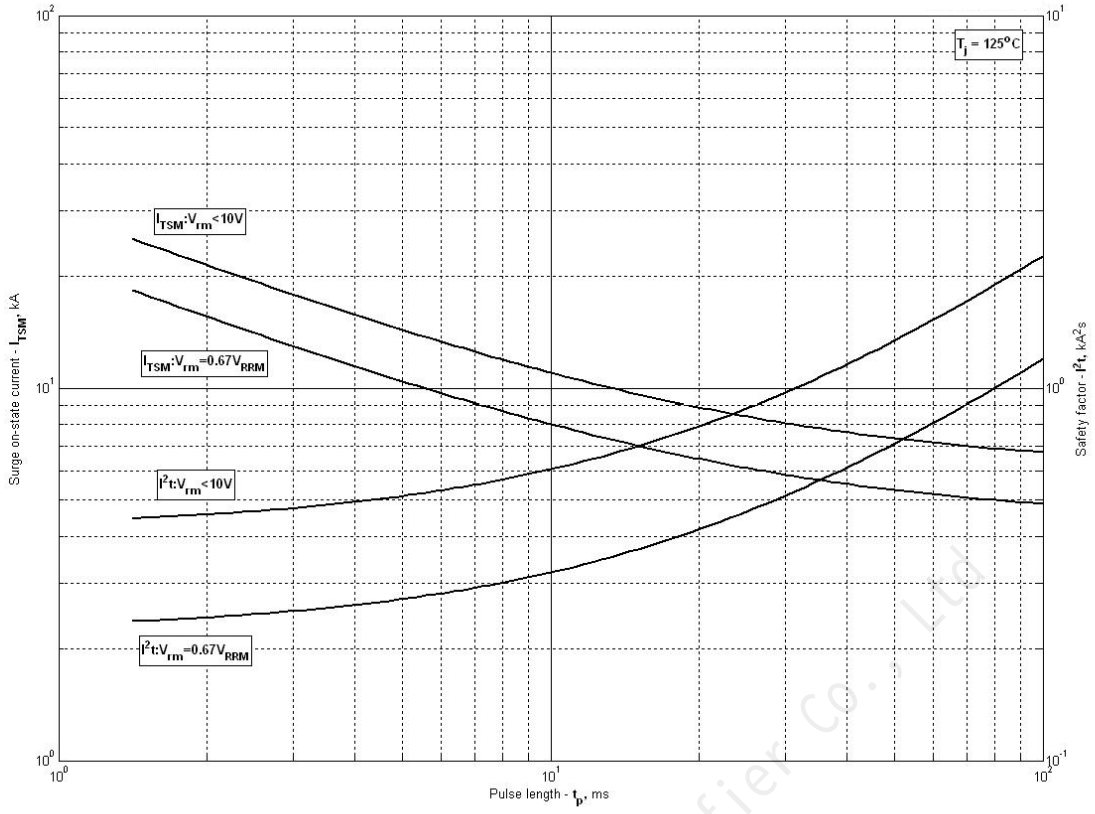


Fig 13 – Maximum surge and I^2t ratings

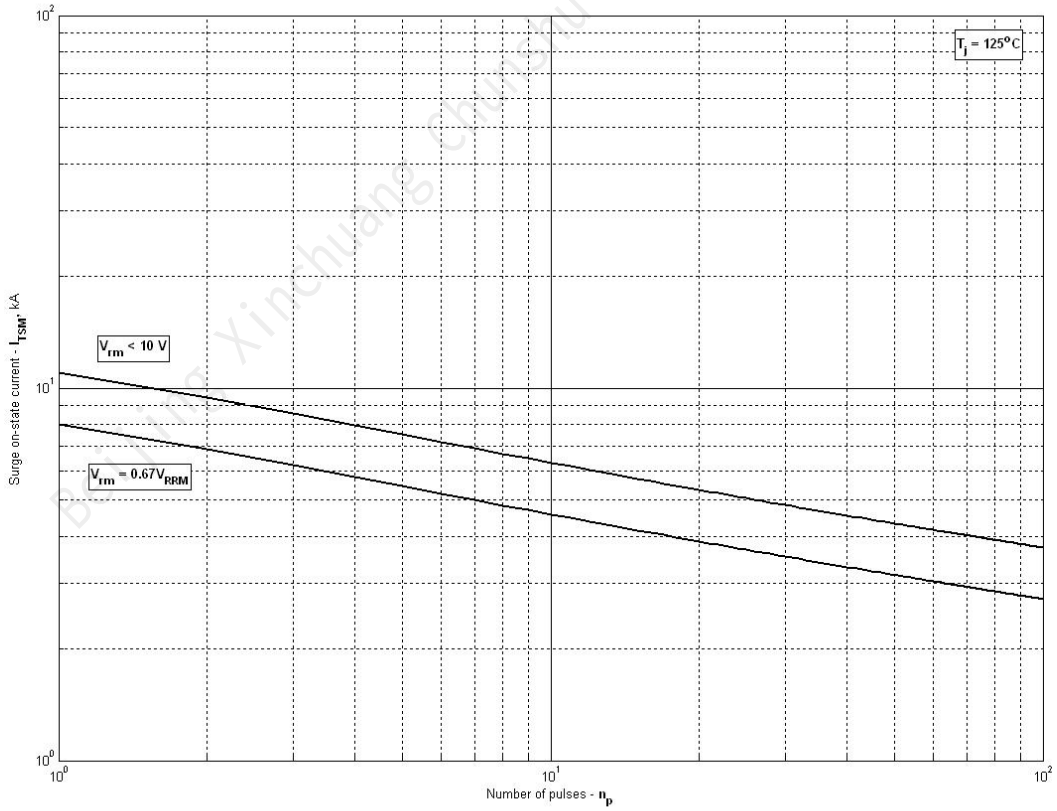


Fig 14 – Maximum surge ratings

